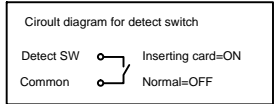


RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)
XKB Connectivity

- PAD AREA
- PATTERN PROHIBITION AREA
- SOLDER PROHIBITION AREA
- PROHIBITED AREA



XKB Connectivity

Specification

1.材料 MATERIAL:

- 1.1 Insulator High Temperature Thermoplastic (LCP MG350), UL Black 94V-0.
- 1.2 端子 Contact: Phosphor Bronze C5210R-H.T=0.15t 0.03mm
- 1.3 外壳 Shell: SUS304-H T-0.12+0.03mm

2.电镀 Plating:

- 2.1 端子 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 100u"min Sn over Ni on solder area
- 2.2 外壳 Shell: Plated 50u"min Ni Overall
Plated 1u"min Au Selective Contact Area

3.性能 Property:

- 3.1 额定电流 Current Rating :05A AC/DCmax
- 3.2 额定电压 Voltage Rating :3.3V/5V(AC/DC)
- 3.3 接触电阻 Contact Resistance; Contact Pin 100mΩ max.
- 3.4 插拔力 Insert/Pulling Force: 40N Max / 0.5~40N
- 3.5 焊接温度 Smt Solder Temperature: Should Under 260 °C
- 3.6 工作温度范围 Operation Temperature Range: -40 °C ~+85 °C

XKB Connectivity

PIN	T/F CARD
	microSD
8	P8 Dat1
7	P7 Dat0
6	P6 VSS
5	P5 CLK
4	P4 VDD
3	P3 CMD
2	P2 CD/Dat3
1	P1 Dat2

DSND		DATE		SCALE: N/A	MODEL TYPE: TF CARD CONN
DWN		DATE		VIEW:	PART NO.:
CHKD		DATE		UNIT: mm/in	DWG NO.:
APPD		DATE		SIZE: A4	XKTF-1251-1
				XKB INDUSTRIAL PRECISION CO., LIMITED	WEIGHT 1.0g
					SHEET 1/1
					REVISION A0

ANGLAR	±5°
L ≤ 4	±0.2
4 < L ≤ 16	±0.3
16 < L ≤ 63	±0.4
L > 63	±0.5
UNSPECIFIED TOLERANCES	

MARK	DESCRIPTION	DATE	REVISED	APPROVED	REVISIONS
ΔX					
ΔX					
ΔX					
MARK					

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